I hereby certify that this correspondence is being deposited with the United States with sufficient postage as first class mail in an envelope addressed to the comm for Patents P.O. Box 1450, Alexandria, VA 22313-1450:

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.

10/090,289

Confirmation No. 6619

Applicant

Johann Winderl

Filed

March 4, 2002

TC/A.U.

2827

Examiner

: Luan C. Thai

Title:

: Electronic Component with Stacked

Semiconductor Chips

Docket No.

MAS-FIN-153

Customer No.

24131

Hon. Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

## **AMENDMENT**

## Sir:

In response to the Office action dated January 6, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing o

claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.

TECHNOLOGY CENTER 2800